DDR4 SODIMM 260P 5.2H STD V ACTIVE

DDR4 DIMM

TE Part # 2309409-1 TE Internal #: 2309409-1

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Connectors > Card & Socket Connectors > Memory Sockets > SO DIMM Sockets



DRAM Type: Small Outline (SO)

Stack Height: 5.2 mm [.205 in]

Module Orientation: Right Angle

PCB Mounting Style: Surface Mount

Connector System: Cable-to-Board

Features

Product Type Features

Center Post	Without
DRAM Type	Small Outline (SO)
Connector System	Cable-to-Board
Profile	Low
Row-to-Row Spacing	8.2 mm[.322 in]
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board
Product Type	Socket

Configuration Features

Center Key	Offset Left
Number of Keys	1
Module Orientation	Right Angle
Number of Positions	260
Number of Rows	2
Keying	Standard
Electrical Characteristics	
DRAM Voltage	1.2 V

Signal Characteristics

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SGRAM Voltage	1.2 V
Body Features	
Ejector Location	Both Ends
Latch Material	High Temperature Thermoplastic
Retention Post Location	Both Ends
Module Key Type	Offset Left
Ejector Type	Locking
Contact Features	
Socket Style	SO DIMM
PCB Contact Termination Area Plating Material	Gold Flash
Contact Base Material	Copper Alloy
Contact Mating Area Plating Material	Gold Flash
Contact Current Rating (Max)	.5 A
Socket Type	Memory Card
Termination Features	
Insertion Style	Cam-In
Mechanical Attachment	
PCB Mount Retention	With
PCB Mount Retention Type	Solder Peg
PCB Mounting Style	Surface Mount
Connector Mounting Type	Board Mount
Housing Features	
Centerline (Pitch)	.5 mm, 3.3 mm[.0197 in][.129 in]
Housing Color	Black
Housing Material	High Temperature Thermoplastic
Dimensions	
Stack Height	5.2 mm[.205 in]
Usage Conditions	
Operating Temperature Range	-55 – 85 °C[-67 – 185 °F]
Operation/Application	
Circuit Application	Power

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UL Flammability Rating	UL 94V-0
Packaging Features	
Packaging Method	Tape & Reel
Packaging Quantity	800

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JAN 2019 (197) Candidate List Declared Against: JAN 2019 (197)
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Reflow solder capable to 260°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulations, TE's information on SVHC in articles for this part number is still based on the European Chemical Agency (ECHA) 'Guidance on requirements for substances in articles' (Version: 2, April 2011), applying the 0.1% weight on weight concentration threshold at the finished product level. TE is aware of the European Court of Justice ruling of September 10th, 2015 also known as O5A (Once An Article Always An Article) stating that, in case of 'complex object', the threshold for a SVHC must be applied to both the product as a whole and simultaneously to each of the articles forming part of its composition. TE has evaluated this ruling based on the new ECHA "Guidance on requirements for substances in articles" (June 2017, version 4.0) and will be updating its statements accordingly.

Also in the Series | DDR4 DIMM

TE Part # 2309409-1 TE Internal #: 2309409-1





DIMM Sockets(70)



SO DIMM Sockets(39)

Customers Also Bought



TE Part #2227580-1 1X1 R/A ASSY, MINI SAS HD INTERNAL



TE Part #1-2199230-5 M.2 0.5PITCH 4.2H KEY M 15U'' AU



TE Part #2227595-1 1X1 VERT ASSY, MINI SAS HD INTERNAL



TE Part #2199230-4 M.2 0.5PITCH 4.2H KEY E 15U'' AU



TE Part #2274845-1 CFP2 RECEPTACLE ASSEMBLY



TE Part #2309407-1
DDR4 SODIMM 260P 4.0H
STD



TE Part #2309410-1
DDR4 SODIMM 260P 5.2H
RVS



TE Part #2309413-1
DDR4 SODIMM 260P 9.2H
STD



TE Part #3-1734592-4
FPC CONN. 0.5MM PITCH
B/C, 34P



TE Part #6-440129-3 HPI 2.0MM,HSG,3POS, BLACK

Documents

Product Drawings

DDR4 SODIMM 260P 5.2H STD

English

CAD Files

3D PDF

3D

Customer View Model ENG_CVM_CVM_2309409-1_1.2d_dxf.zip

DDR4 SODIMM 260P 5.2H STD

TE Part # 2309409-1 TE Internal #: 2309409-1



English

Customer View Model

ENG_CVM_CVM_2309409-1_1.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_2309409-1_1.3d_stp.zip

English

Product Specifications

Application Specification

English